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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/614,892	07/09/2003	Cheng-Ming Yih	4425-306	4425-306 8433	
7	590 09/07/2004		EXAMINER		
LOWE HAUPTMAN GILMAN			TRAN, MAI HUONG C		
& BERNER, LLP Suite 310		ART UNIT	PAPER NUMBER		
1700 Diagonal Road			2818		
Alexandria, VA 22314			DATE MAILED: 09/07/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	N				
	10/614,892	YIH ET AL.	(K				
Office Action Summary	Examiner	Art Unit					
	Mai-Huong Tran	2818					
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply sispecified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).							
Status							
1) Responsive to communication(s) filed on 29 A	oril 2004.						
	action is non-final.						
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
4) ☐ Claim(s) 1-17 is/are pending in the application 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-17 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	wn from consideration.						
Application Papers							
9) The specification is objected to by the Examiner.							
)⊠ The drawing(s) filed on <u>09 July 2003</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
	Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicat rity documents have been receiv u (PCT Rule 17.2(a)).	ion No ed in this Nationa	al Stage				
Attachment(s)							
1) Notice of References Cited (PTO-892)	4)						
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	5) Notice of Informal F		ГО-152)				

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DETAILED ACTION

Claim Rejections - 35 U.S.C. § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1- 17 are rejected under 35 U.S.C. 103 (a) as being unpatentable over U.S. Patent No. 6,248,641 to Liu et al. (hereinafter Liu) in view of Doong et al. (6,429,081) (hereinafter Doong).

Regarding to claims 1, 2 and 7, Liu discloses a semiconductor device comprising a substrate 11; at least a trench isolation device that comprises a first portion on the substrate and a second portion in the substrate (fig. 2G); a spacer 23a at a sidewall of the first portion, wherein the spacer covers a corner between the sidewall and the substrate 11 as set forth in col. 2, lines 40-67, col. 3, lines 1-14, and figures 2D, 2G.

However, Liu does not disclose at least a nonvolatile memory using trench isolation device. Doong teaches a flash memory which is a nonvolatile memory using trench isolation device (col. 4, lines 53-67).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to form the trench isolation device of Liu into the nonvolatile memory as taught by Doong in order to have high reliability of the flash memories (col. 1, lines 23-24) and to improve programming speed and data retention (col. 4, lines 18-19).

Regarding to claims 3, 11, and 16, Liu discloses the structure wherein the spacer is deposited silicon dioxide (col. 2, lines 62-67, col. 3, line 1, and col. 3, line 18).

Regarding to claims 4, 12, and 17, Liu discloses the claimed invention except for the structure wherein the spacer is deposited silicon nitride or other isolated materials. However, Doong discloses the structure wherein the spacer is deposited silicon nitride (col. 8, lines 44-46).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to form the structure wherein the spacer is deposited silicon nitride, as taught by Doong in order to have high reliability (col. 1, lines 23-24) and to improve programming speed and data retention (col. 4, lines 18-19).

Regarding to claims 5, 10, and 15, Liu discloses the structure wherein a formation of the spacer comprises following steps of depositing a dielectric material layer 17 onto the substrate 11 and the trench isolation device 12; and etching the dielectric material

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layer to form the spacer 23a at the sidewall of the first portion (col. 3, lines 5-20, and fig. 2G).

Regarding to claims 6 and 8, Liu discloses the structure wherein the trench isolation device is shallow trench isolation (col. 3, lines 13, and fig. 2G).

Regarding to claim 9, Liu discloses the claimed invention except for the nonvolatile memory is flash memory. Doong discloses the nonvolatile memory is flash memory (col. 6, line 7).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to form the nonvolatile memory that is a flash memory, as taught by Doong in order to have high reliability of the flash memories (col. 1, lines 23-24) and to improve programming speed and data retention (col. 4, lines 18-19).

Regarding to claim 13, Liu discloses the claimed invention except for the nonvolatile memory comprises a tunnel oxide layer. Doong teaches the nonvolatile memory comprises a tunnel oxide layer 412 (col. 9, lines 32-35, and fig. 14b).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to form the nonvolatile memory that comprises a tunnel oxide layer, as taught by Doong in order to have high reliability of the flash memories (col. 1, lines 23-24) and to improve programming speed and data retention (col. 4, lines 18-19).

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Regarding to claim 14, Liu discloses a semiconductor device comprising a substrate 11; a shallow trench isolation comprises a first portion on the substrate and a second portion in the substrate (fig. 2G); a spacer 23a at a sidewall of the first portion of the shallow trench isolation, wherein the spacer covers a corner between the sidewall and the substrate 11 as set forth in col. 2, lines 40-67, col. 3, lines 1-14, and figures 2D, 2G.

However, Liu does not disclose at least a flash memory between two shallow trench isolations. Doong teaches a flash memory between two shallow trench isolations (col. 4, lines 53-67 and fig. 21b).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to form a flash memory between two shallow trench isolations, as taught by Doong in order to have high reliability of the flash memories (col. 1, lines 23-24) and to improve programming speed and data retention (col. 4, lines 18-19).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Mai-Huong Tran whose telephone number is (571)272-1796. The examiner can normally be reached on 8:00-4:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Nelms can be reached on (571)272-1787. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Mai-Huong Tran

Examiner

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